



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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# 2SC4808J

## Silicon NPN epitaxial planar type

For UHF band low-noise amplification

### ■ Features

- Low noise figure NF
- High forward transfer gain  $|S_{21c}|^2$
- High transition frequency  $f_T$
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing.

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

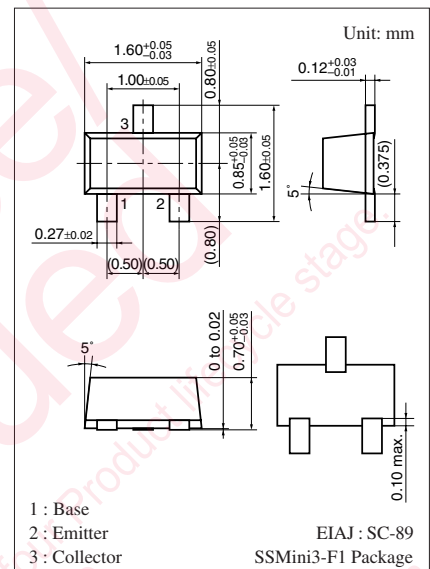
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	15	V
Collector-emitter voltage (Base open)	$V_{CEO}$	10	V
Emitter-base voltage (Collector open)	$V_{EBO}$	2	V
Collector current	$I_C$	80	mA
Collector power dissipation	$P_C$	125	mW
Junction temperature	$T_j$	125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

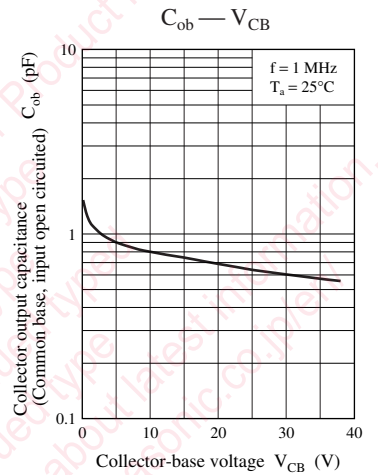
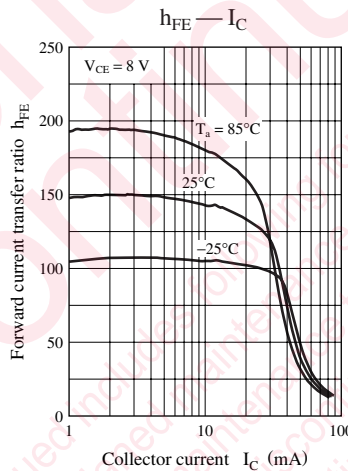
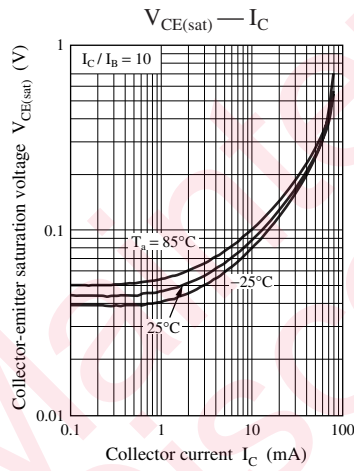
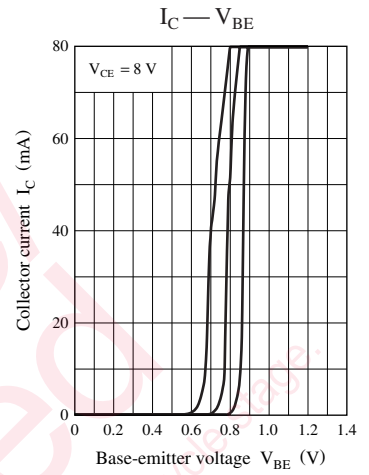
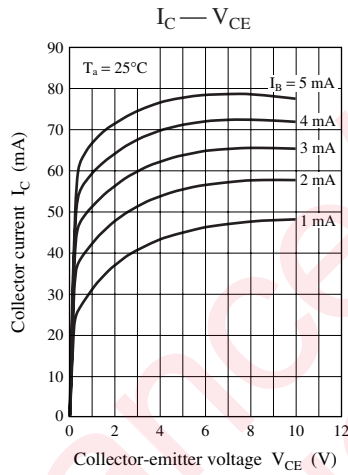
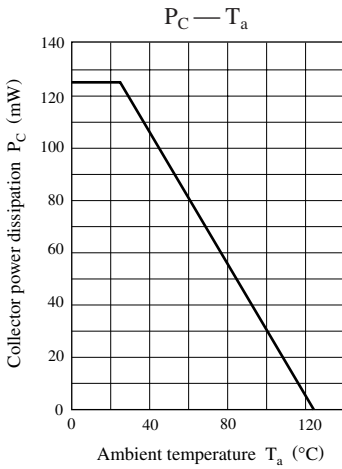
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = 10 \mu\text{A}, I_E = 0$	15			V
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = 100 \mu\text{A}, I_B = 0$	10			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 10 \text{V}, I_E = 0$			1	$\mu\text{A}$
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 2 \text{V}, I_C = 0$			1	$\mu\text{A}$
Forward current transfer ratio *	$h_{FE}$	$V_{CE} = 8 \text{V}, I_C = 20 \text{mA}$	50	150	300	—
Transition frequency	$f_T$	$V_{CE} = 8 \text{V}, I_C = 15 \text{mA}, f = 0.8 \text{GHz}$	5	6		GHz
Collector output capacitance (Common base, input open circuited)	$C_{ob}$	$V_{CB} = 10 \text{V}, I_E = 0, f = 1 \text{MHz}$		0.7	1.2	pF
Forward transfer gain	$ S_{21c} ^2$	$V_{CE} = 8 \text{V}, I_C = 15 \text{mA}, f = 0.8 \text{GHz}$	11	14		dB
Maximum unilateral power gain	$G_{UM}$	$V_{CE} = 8 \text{V}, I_C = 15 \text{mA}, f = 0.8 \text{GHz}$		15		dB
Noise figure	NF	$V_{CE} = 8 \text{V}, I_C = 7 \text{mA}, f = 0.8 \text{GHz}$		1.3	2.0	dB

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*: Pulse measurement



Marking Symbol: 3M



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